

## **ABSTRACT OF THE DISCLOSURE**

The invention relates to a viscosity reducible radiation curable composition comprising at least one radiation curable component and a filler, wherein the composition has the properties i) a yield stress value of  $< 1100 \text{ Pa}$ , ii) a viscosity (at a shear rate of  $1 \text{ sec}^{-1}$ ) between 1 and  $1500 \text{ Pa}\cdot\text{sec}$ , and iii) a filler settling speed less than  $0.3 \text{ mm/day}$ .